

Comment	Designator	Model:Footprint
0.1	C1, C2, C3, C4, C5, C6, C7, C8, C9, C12, C16, C17, C18, C19, C20	Chip Capacitor, Body 1.0x0.5mm, IPC High Density
25v 4700μ	C10	
10v 1000μ	C11	Capacitor, Radial, Pin spacing 3.5mm - Body Diameter 8.5mm x Body Height 13mm
22p	C13, C14	Chip Capacitor, Body 1.0x0.5mm, IPC High Density
10n	C15	Chip Capacitor, Body 1.0x0.5mm, IPC High Density
10A10	D1	
FR307	D2, D3, D4, D5	
Device	D6, D7, IC1	SOD80C, MELF Diode, 2-Leads, Body 3.5x1.5mm, IPC Medium Density, SOD80C, MELF Diode, 2-Leads, Body 3.5x1.5mm, IPC Medium Density, TME Series , Body 11.75x7.25mm, SIP-4 Package
FL817	IC2, IC3, IC4, IC5, IC6	DIP; 4 Leads; Row Spacing 7.62 mm; Pitch 2.54 mm
Main Power	J1	
Motor	J2	
ISP Prog	J3	6 Contacts - Pitch 2.54mm - Dual Row Straight Strip Header - Insulator 1.7mm
Angle Sensor	J4	2.54mm (.100") Pitch KK® Wire-To-Board Header, Right Angle, With Friction Lock, 3 Circuits
Input Signal	J5	2.54mm (.100") Pitch KK® Wire-To-Board Header, Right Angle, With Friction Lock, 2 Circuits
Color	LD1, LD2, LD3	LED, Green, Body Dia. 5.08mm, Pin spacing 2.54mm, 5mm Infrared Emitting Diode, VISHAY TSAL, LED, Red, Body Dia. 5.08mm, Pin spacing 2.54mm
8Mhz	Q1	HC-49/U Leaded Cristal, Body 11.05x4.8mm; Pitch 4.88mm
1k	R1, R2, R4, R5, R6, R7, R8, R11, R12, R13, R14, R15, R16, R18, R19, R20	Resistor, Axial, Pad spacing 10.16 mm - Body Length 6.5mm X Body Diameter 2.5mm, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Resistor, Axial, Pad spacing 10.16 mm - Body Length 6.5mm X Body Diameter 2.5mm, Resistor, Axial, Pad spacing 10.16 mm - Body Length 6.5mm X Body Diameter 2.5mm, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Resistor, Axial, Pad spacing 10.16 mm - Body Length 6.5mm X Body Diameter 2.5mm, Resistor, Axial, Pad spacing 10.16 mm - Body Length 6.5mm X Body Diameter 2.5mm, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density, Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density
510om	R3, R9	Resistor, Axial, Pad spacing 10.16 mm - Body Length 6.5mm X Body Diameter 2.5mm
10k	R10, R17	Chip Resistor, EIA 1206, Metric 3116, Body 3.1x1.55mm, IPC Medium Density
IRFR5305	T1, T3	TO-252AA DPAK TO, 2.28mm pitch; 2 pin,9.905mm L X 6.095mm W X 2.39mm H body, IPC Medium Density
IRLR2905	T2, T4	TO-252AA DPAK TO, 2.28mm pitch; 2 pin,9.905mm L X 6.095mm W X 2.39mm H body, IPC Medium Density
ATmega168PA-AU	U1	Thin QFP, 32-Leads, Body 7x7mm, Pitch 0.8mm, IPC Low Density

